

Date: Sep 2013
Rev: V
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.20
Pot Life: N/A
Shelf Life: One year at room temperature

Recommended Cure:
 100mW/cm² @ 240-365 nm for >2 minutes,
 depending on thickness - under an F-type Mercury lamp

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use. Thermal post-cure beneficial - contact techserv@epotek.com for recommendations.

Product Description: EPO-TEK[®] OG116-31 is a single component, UV curable epoxy adhesive and encapsulant, designed for PCB and circuit assembly applications found in semiconductor, computer, medical, and scientific/OEM industries.

Typical Properties:

*To be used as a guide only, not as a specification. Different batches, conditions & applications yield differing results.
 Cure condition: varies as required * denotes test on lot acceptance basis Data below is not guaranteed.*

PHYSICAL PROPERTIES:	
* Color (before cure):	Cloudy White
* Consistency	Viscous liquid
* Viscosity (23°C): @ 10 rpm	20,000-30,000 cPs
Thixotropic Index:	1.3
* Glass Transition Temp:	≥ 115 °C (Dynamic Cure:20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min)
Coefficient of Thermal Expansion (CTE):	
Below Tg:	41 x 10 ⁻⁶ in/in°C
Above Tg:	170 x 10 ⁻⁶ in/in°C
Shore D Hardness:	83
Die Shear @ 23°C:	≥ 10 Kg 3,400 psi
Degradation Temp:	409 °C
Weight Loss: @ 200°C	0.31 %
@ 250°C	0.68 %
@ 300°C	1.18 %
OperatingTemp: : Continuous:	- 55°C to 200°C
Intermittent:	- 55°C to 300°C
Storage Modulus:	263,581 psi
* Particle Size:	≤ 20 microns

OPTICAL PROPERTIES @ 23°C:	
Spectral Transmission:	≥ 96% @ 660-1640 nm ≥ 92% @ 500 nm
Refractive Index (uncured):	1.5665 @ 589 nm
Refractive Index (cured):	1.5842 @ 589 nm

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPO-TEK[®] OG116-31 Advantages & Suggested Application Notes:

- Viscosity/rheology adapted to high volume syringe needle dispensing with no tailing.
- Complies with USP Class VI biocompatibility standards.
- Versatility in cure. Product responds to a broad range of UV light, and secondary thermal post-curing.
- Suggested applications:
 - ◇ Semiconductor: COB glob top covering IC's and wire bonds; glob top dam; encapsulating and sealing; adhesion to FR4, Kapton, silicon.
 - ◇ Fiber Optic: making fiber optic pigtailed; active alignment of optics; adhesion to many types of glass, metals, ceramics and plastics.
 - ◇ Opto-electronic:
 - Perimeter/main seal for LCD's, compatible with VAN liquid crystal for LCoS devices.
 - Adhesive technology described in Technical Paper # 55 - <http://www.epotek.com/technical-papers.asp>
- High Tg and low outgassing are indicative of its high temperature performance.

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EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805 FAX (978) 663-9782

www.epotek.com